DesignDRIVE Kit

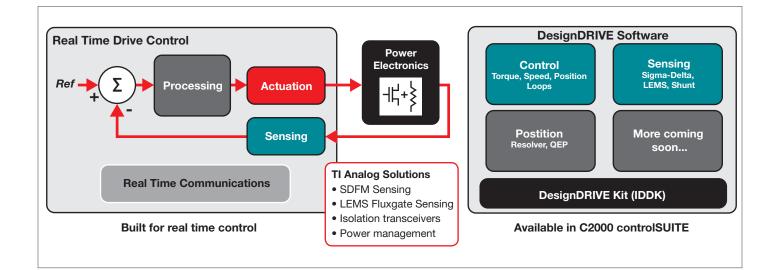


The ONE place to create MANY designs for Industrial Drives

TEXAS INSTRUMENTS

Integrated Drive Controller – Delfino[™] TMS320F2837x C2000[™] MCU

Processing	Actuation	Feedback Interface Circuits
Up to 800 MIPS (Dual Core)	• Up to 24 ch Flexible PWM	Quad 16 bit/12 bit ADCs
Trigonometric Math Unit	• 3 phase to multil-level	Sinc Filters with compare
• Up to 1MB flash	Programmable Trip Zones	AMC130x, AMC120x compliant
Up to 204KB SRAM	Safety diagnostics	LEMS, Shunt topologies



Flexible System Expansion Support

Industrial Connectivity	Functional Safety	Position Encoder Feedback
• Expansion slot for future enhancements	• Expansion slot for future enhancements	EnDatSinCosBiSSQEPResolver

Getting Started

DesignDRIVE Kit: www.ti.com/tool/tmdxiddk377 Delfino™ MCU: www.ti.com/tool/tmdxdock28377d DeltaSigma Mod: http://www.ti.com/tool/TIDA-00171	TMDXIDDK377 TMDXIDDK377D-MTR-BNDL	\$ 999 \$1,199	
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Current Measurement Topology Comparison and Real-time Control Performance Evaluation

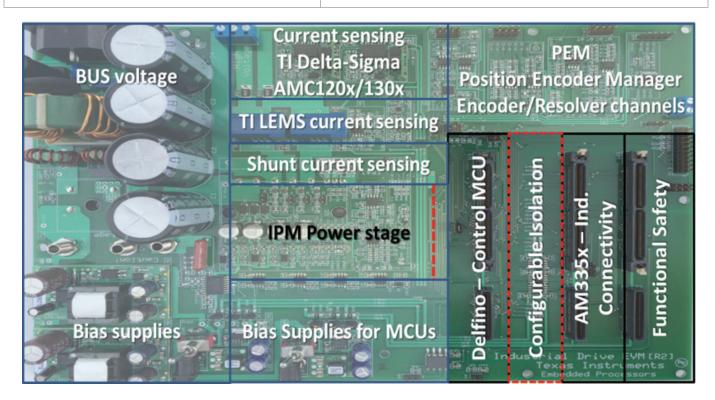
SDFM Current Sense	Park Transform cyc	$ \begin{bmatrix} \hat{l}_d \\ \hat{l}_q \\ \hat{l}_o \end{bmatrix} = \begin{bmatrix} \cos(\theta) & \sin(\theta) & 0 \\ -\sin(\theta) & \cos(\theta) & 0 \\ 0 & 0 & 1 \end{bmatrix} $	$X\begin{bmatrix}i_{\alpha}\\i_{\beta}\\i_{o}\end{bmatrix}$
b charter s : anator s anator s	Coding Format	C28-TMU	Com
	Inline C Macro	19	150
	C Function Call	29	150
LEM Current Sense	Resolver Angular P (Using ATAN2 operation)	osition Calculatio	on cycles

Coding Format	C28-TMU	Competition
Inline C Macro	14	100+
C Function Call	24	100+

Competition 150-250 150-250

Field Oriented Control Loop cycles

Motor Type	C28-TMU Min cyc Max		Competition Min cyc Max	
PMSM	547	592	1096	1208
ACInduction	593	670	1260	1387



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Shunt Current Sense



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